

Features

- 0603 0.88mm SMD LED
- Close responsively to the human eye spectrum ·
- Light to Current, analog output ·
- Good output linearity across wide illumination range ·
- Low sensitivity variation across various light sources ·

Applications

- Detection of ambient light to control display backlighting
- Mobile devices
- Computing device
- Consumer device
- Automatic residential and commercial management
- Automatic contrast enhancement for electronic signboard
- Ambient light monitoring device for daylight and artificial light

Description

The IN-S63DTLS is a popular 0603 package with versatile design capabilities. It is a PCB type molding style LED which can be used in various applications.

Recommended Solder Pattern

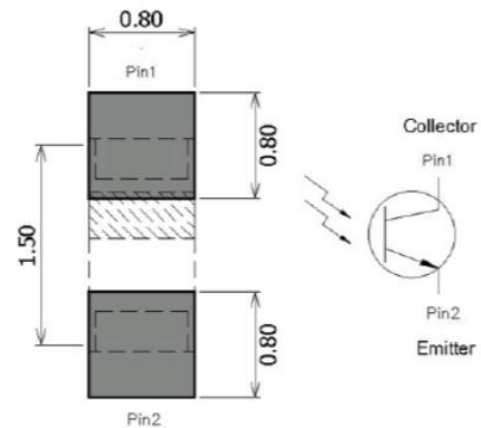
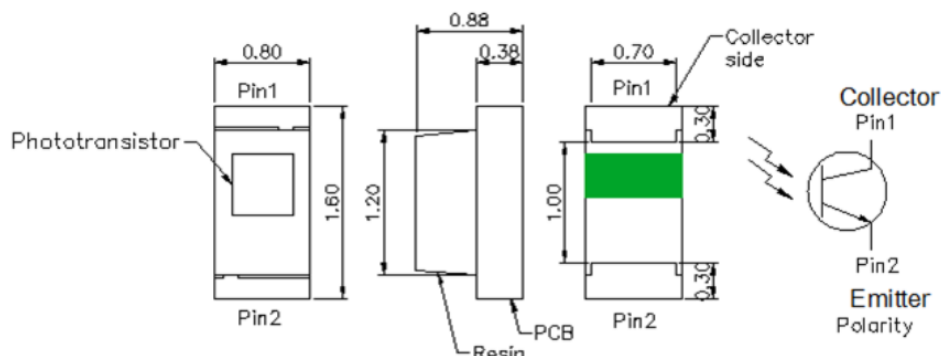


Figure 1. IN-S63DTLS Solder Pattern

Package Dimensions in mm

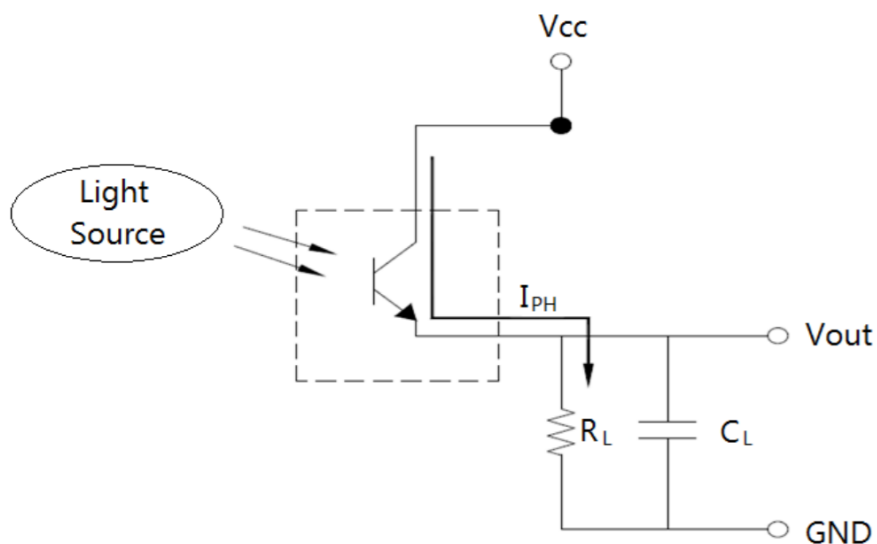


Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise noted.

Figure 2. IN-S63DTLS Package Dimensions

Converting Photocurrent to Voltage



Notes:

1. The output voltage (Vout) is the product of photocurrent (IPH) and loading resistor (RL)
2. A right loading resistor shall be chosen to meet the requirement of maximum ambient light, and output saturation voltage:

$$V_{out(max.)} = I_{PH(max.)} \times R_L \leq V_{out(saturation)} = V_{cc} - 0.4V$$

Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
BV _{CEO}	Collector-Emitter Breakdown Voltage	60	V	1
BV _{ECO}	Emitter-Collector Breakdown Voltage	4	V	2
I _C	Collector Current	20	mA	
T _{opr}	Operating Temperature	-40~+85	°C	
T _{stg}	Storage Temperature	-40~+100	°C	
T _{sol}	Soldering Temperature	260	°C	3

Notes

1. Test conditions: I_C=100μA, E_v=0 Lx.
2. Test conditions: I_E=100μA, E_v=0 Lx.
3. Soldering time ≤ 5 seconds.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

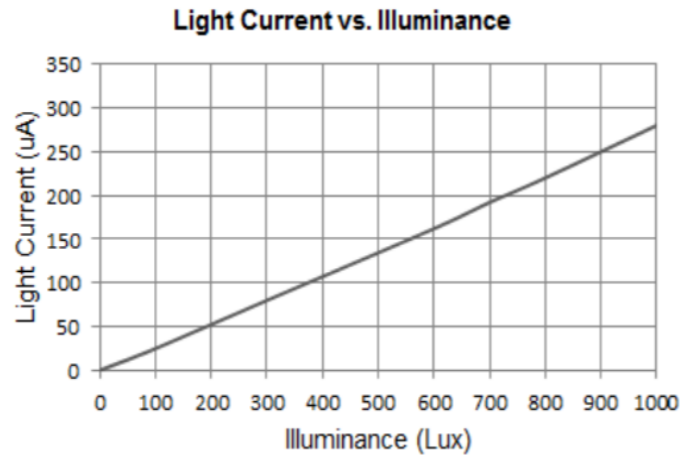
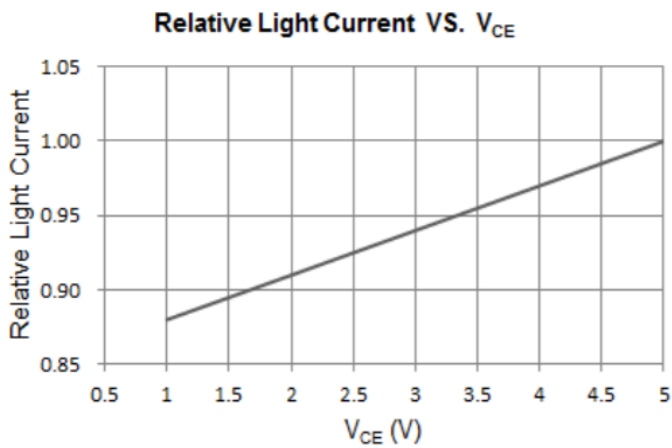
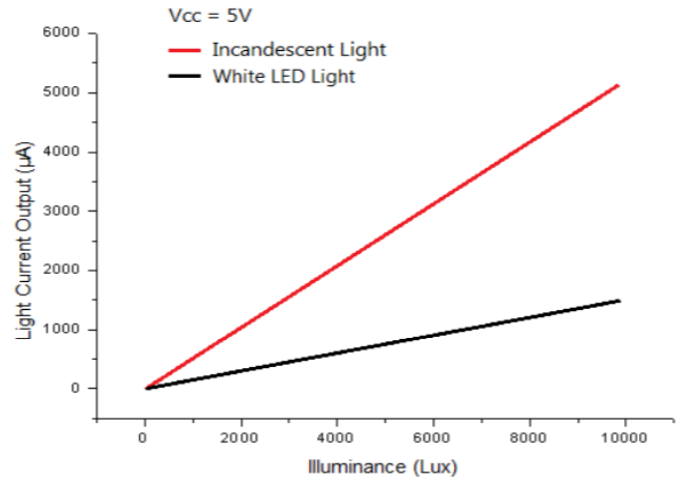
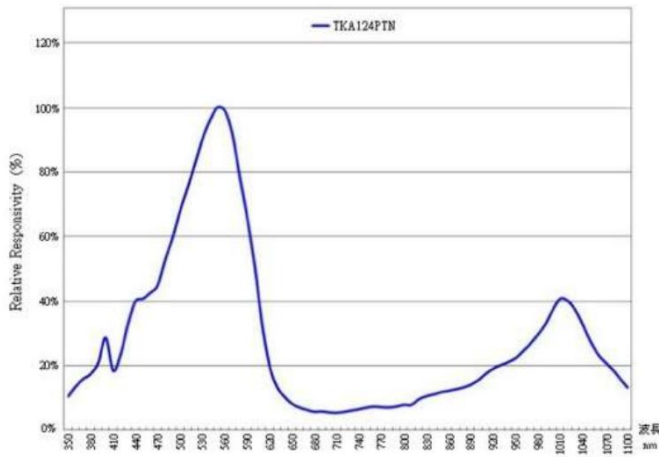
Electro-Optical Characteristics

Symbol	Parameters	Test conditions	Min	Typ	Max	Units	Notes
λ_D	Rang Of Spectral Bandwidth	---	390	-	700	nm	
λ_P	Wavelength Of Peak Sensitivity	---	-	630		nm	
BV _{CEO}	Collector-Emitter Breakdown Voltage	I _C =100 μ A E _v =0 Lx	60	-	-	V	
BV _{ECO}	Emitter-Collector Breakdown Voltage	I _E =100Ma E _v =0 Lx	4	-	-	V	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =2mA E _v =1000 Lx	-	-	0.4	V	
I _{CEO}	Collector Dark Current	V _{CE} =10V E _v =0 Lx	-	-	100	nA	
I _{PH1}	Light Current (1)	V _{CE} =5V , E _v =100 Lx	5	25	50	μ A	1
I _{PH2}	Light Current (2)	V _{CE} =5V , E _v =1000 Lx	50	280	500	μ A	1
I _{PH3}	Light Current (3)	V _{CE} =5V , E _v =1000 Lx	150	620	950	μ A	2
V _O	Saturation Output Voltage	V _{CC} =5V, E _v = 1000 Lx , R _L =75K	4.5	4.6		V	

Notes

1. White LED light (Color Temperature = 6500K) is used as light source.
2. Illuminance by CIE standard illuminant-A / 2856K, incandescent lamp.


Typical Characteristic Curves




Ordering Information

Product	Symbol	Parameters	Test conditions	Min	Typ	Max	Units	Orderable Part Number
IN-S63DTLS	IPH1	Light Current (1)	$V_{CE}=5V$, $E_v=100\text{ Lx}$	5	25	50	μA	IN-S63DTLS
	IPH2	Light Current (2)	$V_{CE}=5V$, $E_v=1000\text{ Lx}$	50	280	500	μA	
	IPH3	Light Current (3)	$V_{CE}=5V$, $E_v=1000\text{ Lx}$	150	620	950	μA	

Label Specifications


Inolux



Date: yyyy/mm/dd
 |||| |||| |||| |||| ||||

CUSTOMER P/N:
 |||| |||| |||| |||| |||| ||||

INOLUX P/N:
 |||| |||| |||| |||| |||| |||| |||| ||||

QTY: PCS
 |||| |||| |||| |||| |||| ||||

LOT NO:
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IV BIN:
 |||| |||| |||| |||| |||| |||| |||| |||| ||||

COLOR BIN:
 |||| |||| |||| |||| |||| |||| |||| |||| ||||

VF:
 |||| |||| |||| |||| |||| |||| |||| |||| ||||

QC
 |||| |||| |||| |||| |||| |||| |||| |||| ||||

Inolux P/N:

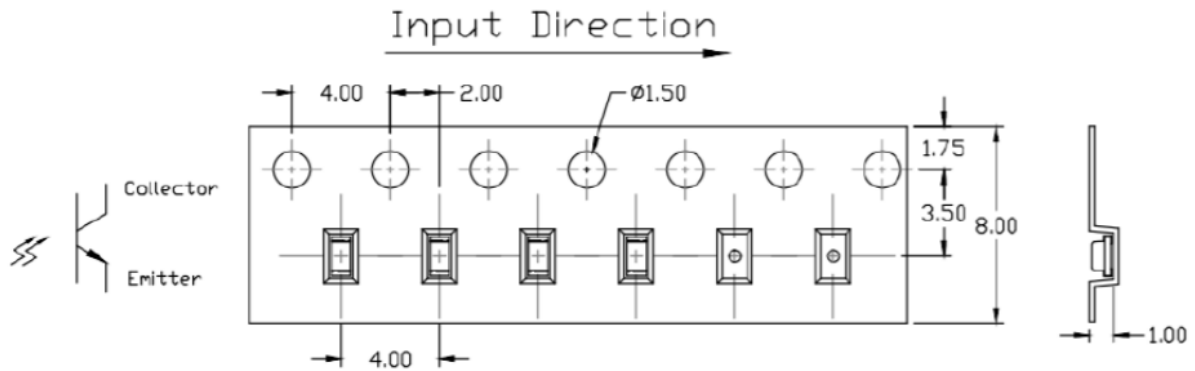
I	N	-	S	6	3	D	T		LS	-	-	-	-	-
Inolux SMD			Material	Package		Variation	Orientation	Lens	Color	Customized Stamp-off				
			S = PCB Type	63D = 0603 0.88mm			T = Top Mount	(Blank) = Clear U = Diffused	LS=Light sensor					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018,)				Month	Date	Serial

Packaging Information: 4000pcs Per Reel

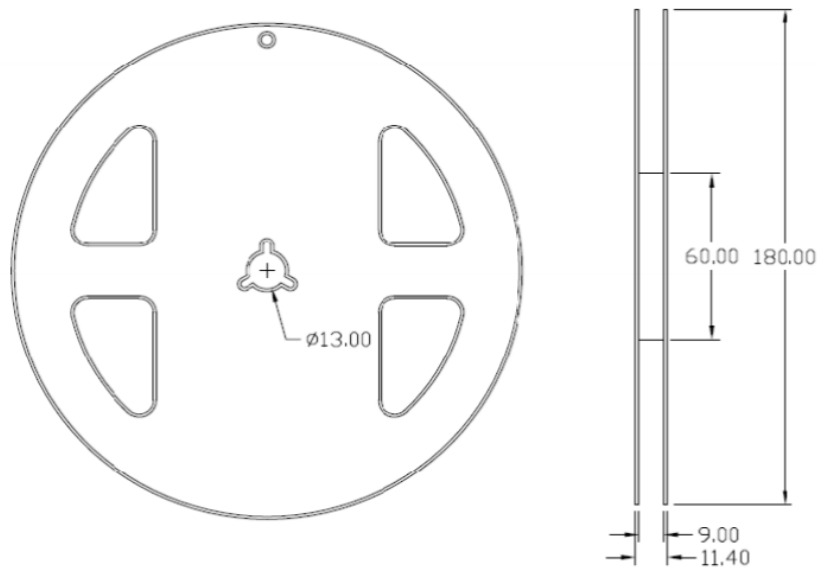
Tape Dimension



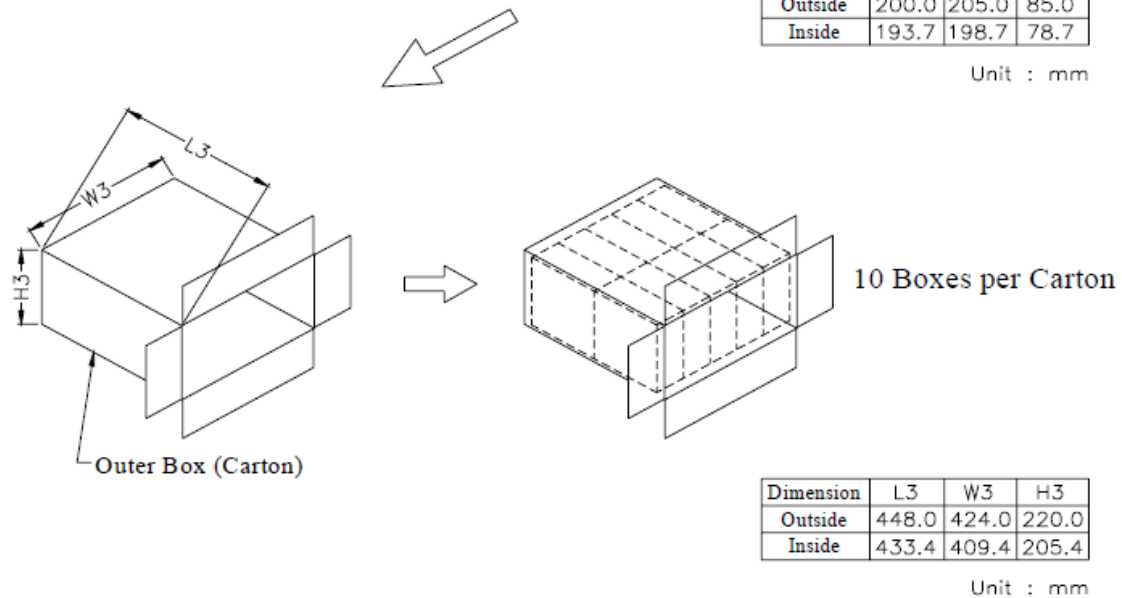
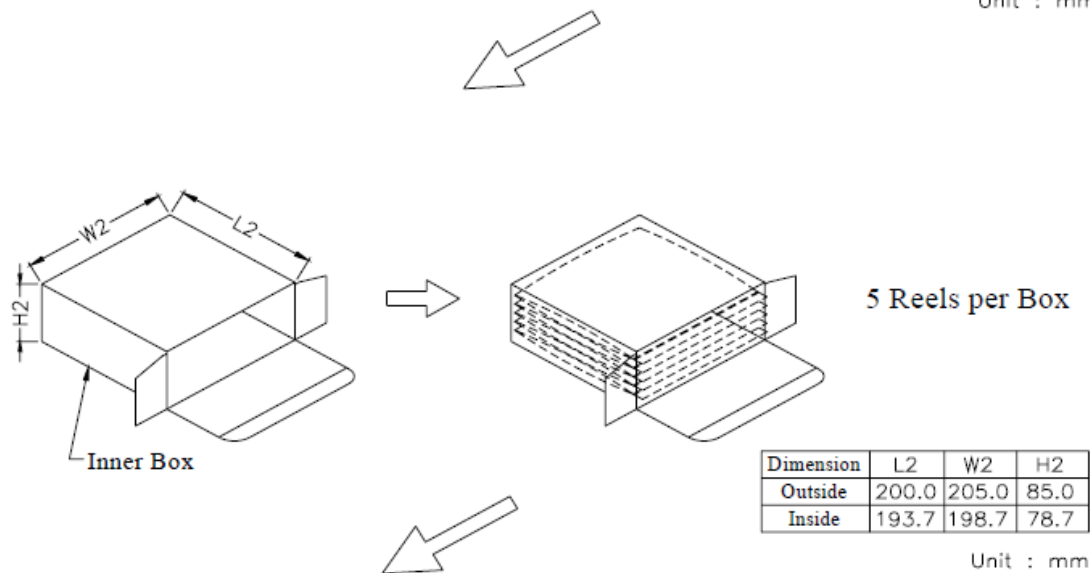
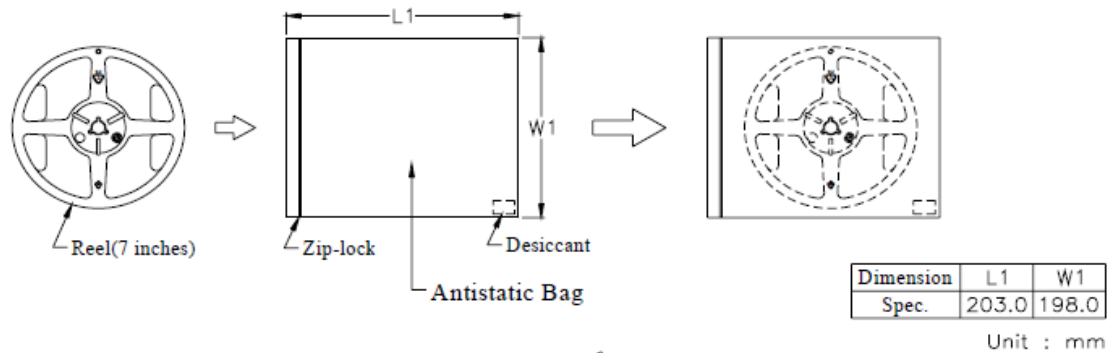
Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.80±0.05	0.94±0.05	1.0±0.05	4K

Unit: mm

Reel Dimension



Packing Dimension

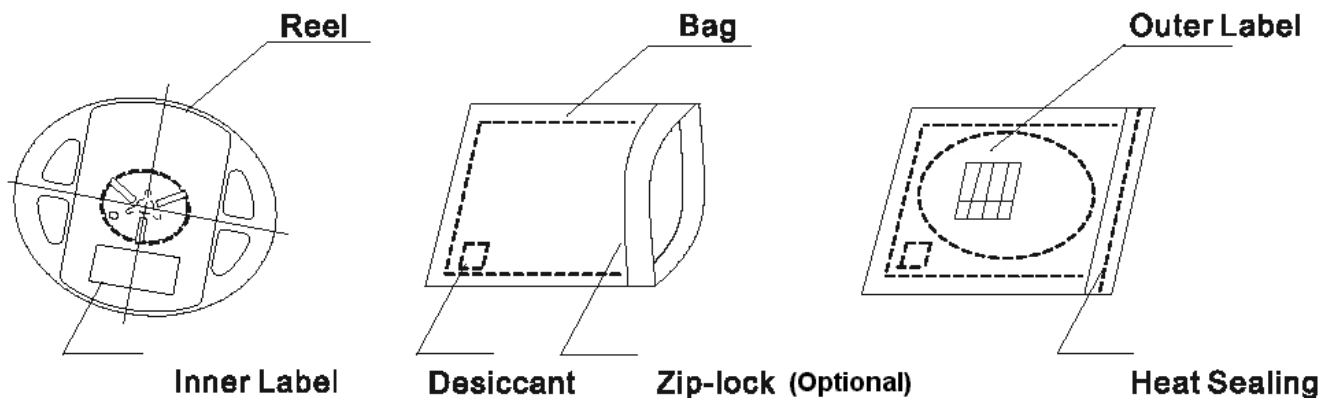


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

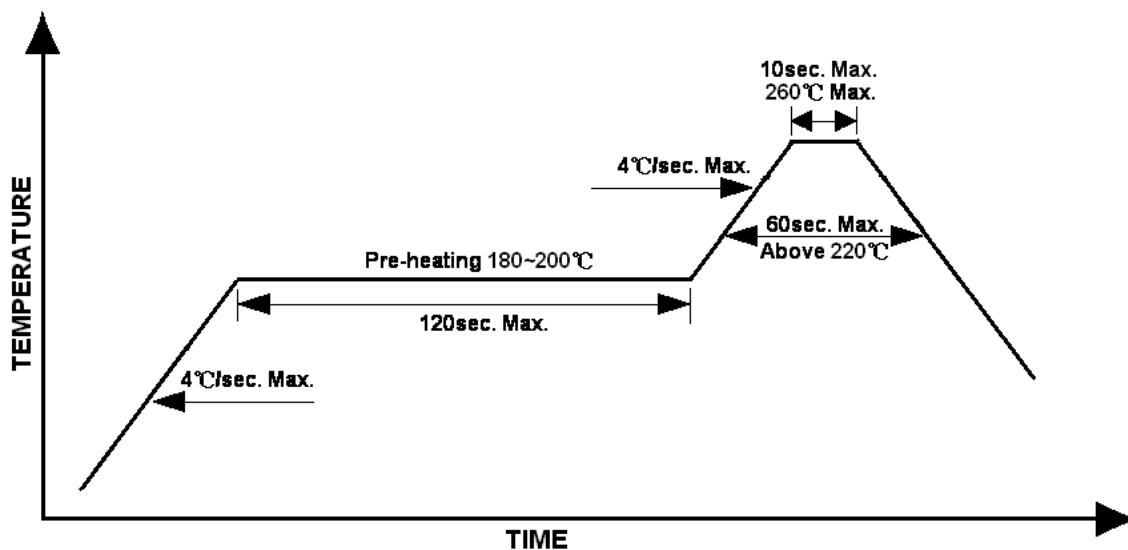
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	11-09-2018
Updated	P1	1.1	01-31-2019
Updated	P3	1.2	09-01-2020
Updated	P5	1.3	08-28-2025
Updated	P1	1.4	12-29-2025

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.